| ASSOCIATION CONNECTING<br>ASSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES®<br>international and Pa | IPC. Bannockl | ourn, Illinois, A           | ll rights reserved untions. | under both              | This docume<br>level parts, t                                       | ent is a declaration entries the declaration entries and t | on of the su | bstances v<br>all lower | vithin the manufactu<br>level materials for v | rer listed in the rest of the | item. Note:<br>nanufacture      | if the item is an as<br>r has engineering | sembly with low responsibility. |  |
|---|---------------|-----------------------------|-----------------------------|-------------------------|---|--|--------------|-------------------------|---|---|---------------------------------|---|---------------------------------|--|
|   |               |                             |                             | Form Type<br>Distribute | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materia |  |              |                         |   | ials and N  | als and Mfg Information         |   |                                 |  |
| Supplier Information  |               |                             |                             |                         |   |  |              |                         |   |   |                                 |   |                                 |  |
| Company name* Compan  |               |                             | mpany unique ID             |                         |   | Unique ID Authority  |              |                         |   | Respon  | Response Date*                  |   |                                 |  |
| onsemi  |               |                             |                             |                         |   |  |              |                         |   | 2024-05-18  |                                 |   |                                 |  |
| ntact Name Title - Contact  |               |                             |                             |                         | Phone - Contact*  |  |              |                         | Email - Contact*                              |   |                                 |   |                                 |  |
| Product-Env-Stewards Product Enviro Comp  |               |                             | ro Compliance               | Compliance              |   | NA   |              |                         |   | Product-Env-Stewards@onsemi.com   |                                 |   |                                 |  |
| Authorized Representative* Title - Representative   |               |                             | entative                    |                         |   | Phone - Representative*  |              |                         | Email - Representative*                       |   |                                 |   |                                 |  |
| Product-Env-Stewards Product H  |               |                             | duct Enviro Compliance      |                         |   | NA   |              |                         |   | Produe  | Product-Env-Stewards@onsemi.com |   |                                 |  |
| Requester Item Number   | Mfr Iten      | n Number                    | Mfr Item Name               |                         |   | Effective Date   | Version      | М                       | Manufacturing Site                            |   | Weight*                         | UOM                                       | Unit Type                       |  |
|   | NLV74         | NLV74AC08DR2G LOG CMOS GATE |                             | TE AND                  |   | 2024-05-18   |              | PI                      | PH1   |   | 122.05                          | mg  | Each                            |  |
| Ianufacturing Proccess Informa  | ition         |                             | ·                           |                         |   |  |              |                         |   |   |                                 |   |                                 |  |
| Terminal Plating / Grid Array M   | aterial       | ial Terminal Base Alloy J-S |                             |                         | L Rating  | Peak Process Body Temperature Max Time at Pe   |              |                         | Max Time at Peal                              | k Temperature Number of Reflow Cycles   |                                 |   |                                 |  |
| Matte Tin (Sn) - annealed CU Alloy  |               |                             | 1                           |                         | 260   |  | С            | 30                      | secor   | nds 3   |                                 |   |                                 |  |
| omments   |               |                             |                             |                         |   |  |              |                         |   |   |                                 |   |                                 |  |
| vel 1 - maximum time at peak temperat   | ure during so | ldering is 10-3             | 0 seconds                   |                         |   |  |              |                         |   |   |                                 |   |                                 |  |
| or more information regarding material  | composition   | please refer to             | page 3                      |                         |   |  |              |                         |   |   |                                 |   |                                 |  |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>y others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the   | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | on above   | Supplier Acceptance   | * Accepted                                      |   |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| sigma range of distribution unless otherwise noted). |        |                 |          |                     |                  |        |         |                 |  |  |
|--|--------|-----------------|----------|---------------------|------------------|--------|---------|-----------------|--|--|
| Homogeneous Material                                 | Weight | Unit of Measure | Level    | Substance           | CAS              | Exempt | Weight  | Unit of Measure |  |  |
| Die  | 0.98   | mg              | Supplier | Silicon (Si)        | 7440-21-3        |        | 0.98    | mg              |  |  |
| Die Attach   | 4.44   | mg              | Supplier | Silver (Ag)         | 7440-22-4        |        | 3.33    | mg              |  |  |
|  |        |                 | Supplier | Epoxy resins        | 129915-35-1      |        | 1.11    | mg              |  |  |
| Lead Frame   | 69.62  | mg              | Supplier | Silver (Ag)         | 7440-22-4        |        | 0.7658  | mg              |  |  |
|  |        |                 | Supplier | Zinc (Zn)           | 7440-66-6        |        | 0.1392  | mg              |  |  |
|  |        |                 | Supplier | Iron (Fe)           | 7439-89-6        |        | 1.8101  | mg              |  |  |
|  |        |                 | Supplier | Copper (Cu)         | 7440-50-8        |        | 66.9048 | mg              |  |  |
| Mold Compound-Black                                  | 43.43  | mg              |          | Epoxy Phenol Resin  | proprietary data |        | 4.5601  | mg              |  |  |
|  |        |                 | Supplier | Fused Silica (SiO2) | 60676-86-0       |        | 38.8699 | mg              |  |  |
| Plating  | 3.27   | mg              | Supplier | Tin (Sn)            | 7440-31-5        |        | 3.27    | mg              |  |  |
| Wire Bond - Au                                       | 0.31   | mg              | Supplier | Gold (Au)           | 7440-57-5        |        | 0.31    | mg              |  |  |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signa range of distribution unless otherwise noted)